



WHAT IS CLAIMED IS:

- 1 1. A method of forming a conductive device, the method
2 comprising:
3 forming a conductive layer on a substrate;
4 etching the conductive layer to form a plurality of conductive traces;
5 etching the conductive layer to form at least one mask feature; and
6 removing substrate material that is not covered by the at least one
7 mask feature so as to form at least one mechanical alignment feature.
- 1 2. The method of claim 1 wherein the etching steps are
2 performed simultaneously.
- 1 3. The method of claim 1 wherein the removing step includes
2 removing the substrate material with a laser.
- 1 4. The method of claim 1 wherein the removing step includes
2 removing the substrate material so as to form at least one aperture.
- 1 5. The method of claim 1 wherein the removing step includes
2 removing the substrate material so as to form at least one side edge.
- 1 6. The method of claim 1 wherein the removing step includes
2 removing the substrate material so as to form at least one tab.
- 1 7. The method of claim 1 wherein the removing step includes
2 removing the substrate material so as to form at least one slot.
- 3 8. A conductive device produced according to the method of
4 claim 1.
- 1 9. A method of forming a printed circuit board, the method
2 comprising:

3 forming a conductive layer on a substrate;
4 etching the conductive layer to form multiple conductive traces,
5 each trace having a contact portion,
6 etching the conductive layer to form multiple mask features that
7 cooperate to define a template; and
8 ablating with a laser substrate material that is not covered by the
9 template so as to form a plurality of mechanical alignment features.

1 10. The method of claim 9 wherein the etching steps are
2 performed simultaneously.

Sub A1
1 11. The method of claim 9 wherein the ablating step comprises
2 ablating substrate material so as to form a multiple apertures and multiple side
3 edges, wherein the apertures and the side edges function as mechanical alignment
4 features.

Sub B1
1 12. A printed circuit board produced according to the method of
2 claim 9.

Add
A2